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May 2008

FDS6690AS

30V N-Channel PowerTrench® SyncFET[™]

General Description

The FDS6690AS is designed to replace a single SO-8 MOSFET and Schottky diode in synchronous DC:DC power supplies. This 30V MOSFET is designed to maximize power conversion efficiency, providing a low $R_{\rm DS(ON)}$ and low gate charge. The FDS6690AS includes an integrated Schottky diode using Fairchild's monolithic SyncFET technology. The performance of the FDS6690AS as the low-side switch in a synchronous rectifier is close to the performance of the FDS6690A in parallel with a Schottky diode.

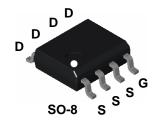
Applications

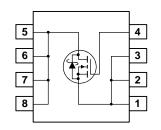
- DC/DC converter
- · Low side notebooks

Features

- 10 A, 30 V. $R_{DS(ON)}$ max= 12 m Ω @ V_{GS} = 10 V $R_{DS(ON)}$ max= 15 m Ω @ V_{GS} = 4.5 V
- Includes SyncFET Schottky diode
- Low gate charge (16nC typical)
- High performance trench technology for extremely low R_{DS(ON)}
- · High power and current handling capability







Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	10	Α
	- Pulsed		50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{STG}	Operating and Storage Junction Temperat	ure Range	-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS6690AS	FDS6690AS	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	1		I	I	I
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ mA}$	30			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C		30		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			500	μА
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1$ mA	1	1.6	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C		-4		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$\begin{split} &V_{GS} = 10 \text{ V}, & I_D = 10 \text{ A} \\ &V_{GS} = 4.5 \text{ V}, & I_D = 8.5 \text{ A} \\ &V_{GS} = 10 \text{ V}, I_D = 10 \text{A}, T_J = 125 ^{\circ}\text{C} \end{split}$		10 12 15	12 15 19	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, \qquad V_{DS} = 5 \text{ V}$	50			Α
g _{FS}	Forward Transconductance	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 10 \text{ A}$		45		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		910		pF
Coss	Output Capacitance	f = 1.0 MHz		270		pF
C _{rss}	Reverse Transfer Capacitance			100		pF
R _G	Gate Resistance	$V_{GS} = 15 \text{ mV}, f = 1.0 \text{ MHz}$		2.0		Ω
Switchin	g Characteristics (Note 2)	•				
t _{d(on)}	Turn-On Delay Time			8	16	ns
t _r	Turn-On Rise Time	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 1 \text{ A},$		5	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		25	40	ns
t _f	Turn-Off Fall Time			6	12	ns
t _{d(on)}	Turn-On Delay Time			11	20	ns
t _r	Turn-On Rise Time	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 1 \text{ A},$		11	20	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		15	27	ns
t _f	Turn-Off Fall Time			8	16	ns
Q _{g(TOT)}	Total Gate Charge at Vgs=10V			16	23	nC
Q_g	Total Gate Charge at Vgs=5V	$V_{DD} = 15 \text{ V}, I_{D} = 10 \text{ A}$		9	13	nC
Q _{gs}	Gate-Source Charge			2.3		nC
Q_{gd}	Gate-Drain Charge			3.0		nC

Electrical Characteristics		TA = 25°C unless otherwise noted					
Symbol	Parameter	Test Condition	ns	Min	Тур	Max	Units
Drain-	-Source Diode Characteristic	s and Maximum Rat	tings				
Is	Maximum Continuous Drain-Source Diode Forward Current					3.5	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 3.5 \text{ A}$	(Note 2)		0.6	0.7	V
Trr	Diode Reverse Recovery Time	$I_F = 10A,$			16		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_t = 300 \text{ A/}\mu\text{s}$	(Note 3)		9		nC

Notes

1. R_{aJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{aJC} is guaranteed by design while R_{aCA} is determined by the user's board design.



a) 50°/W when mounted on a 1 in² pad of 2 oz copper



b) 105°/W when mounted on a .04 in² pad of 2 oz copper



c) 125°/W when mounted on a minimum pad.

- Scale 1:1 on letter size paper
- **2.** Pulse Test: Pulse Width < 300μ s, Duty Cycle < 2.0%
- 3. See "SyncFET Schottky body diode characteristics" below.

Typical Characteristics

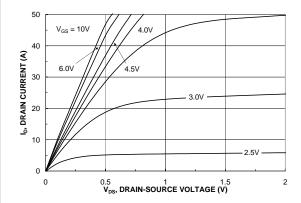


Figure 1. On-Region Characteristics.

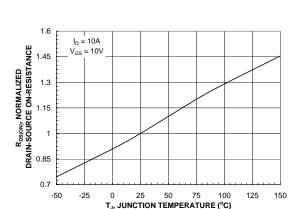


Figure 3. On-Resistance Variation with Temperature.

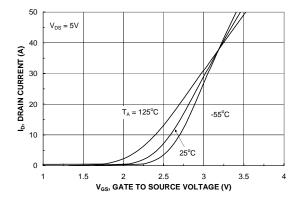


Figure 5. Transfer Characteristics.

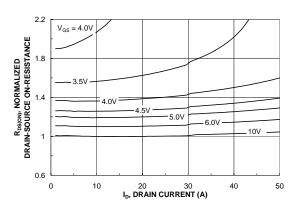


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

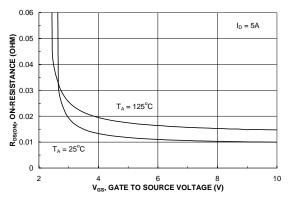


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

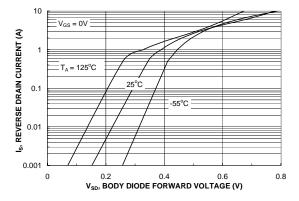


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

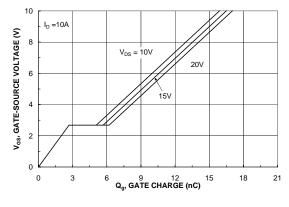
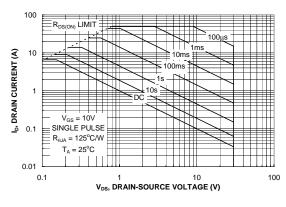


Figure 7. Gate Charge Characteristics.





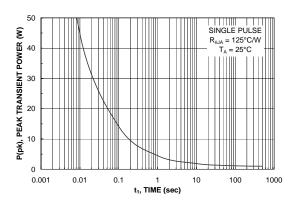


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

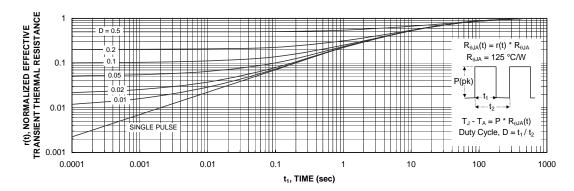


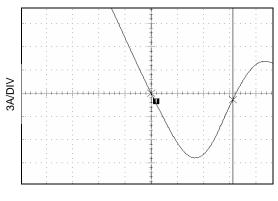
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

Typical Characteristics (continued)

SyncFET Schottky Body Diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 12 shows the reverse recovery characteristic of the FDS6690AS.



10nS/DIV

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

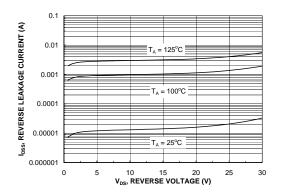


Figure 14. SyncFET body diode reverse leakage versus drain-source voltage and temperature.

Figure 12. FDS6690AS SyncFET body diode reverse recovery characteristic.

For comparison purposes, Figure 13 shows the reverse recovery characteristics of the body diode of an equivalent size MOSFET produced without SyncFET (FDS6690A).

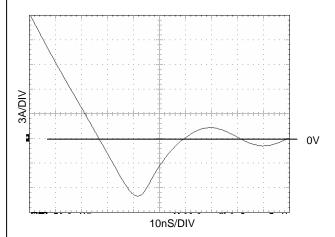
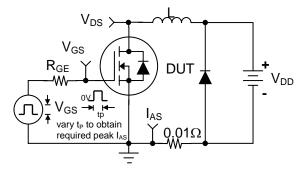


Figure 13. Non-SyncFET (FDS6690A) body diode reverse recovery characteristic.

Typical Characteristics



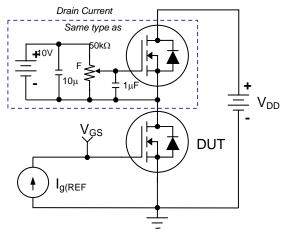
BV_{DSS}

V_{DS}

V_{DD}

Figure 15. Unclamped Inductive Load Test Circuit

Figure 16. Unclamped Inductive Waveforms



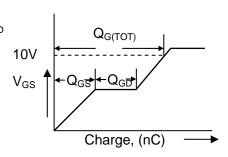
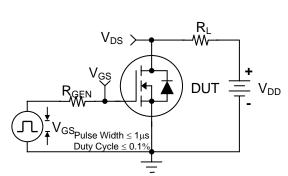


Figure 17. Gate Charge Test Circuit

Figure 18. Gate Charge Waveform



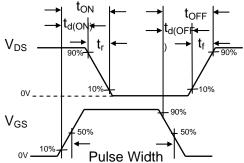


Figure 19. Switching Time Test Circuit

Figure 20. Switching Time Waveforms





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